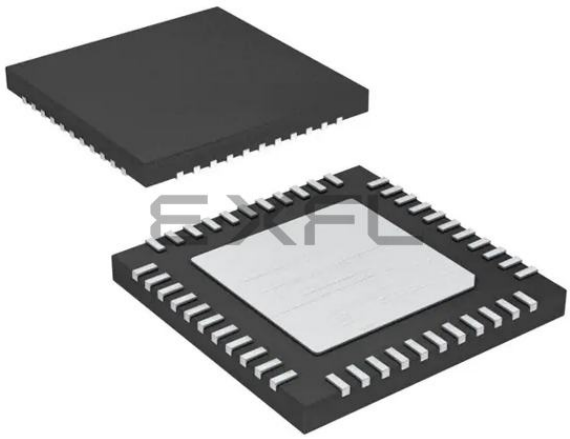

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx220f032d-i-ml

TABLE 14: PIN NAMES FOR 44-PIN USB DEVICES

44-PIN VTLA (TOP VIEW)(1,2,3,5)

PIC32MX210F016D
PIC32MX220F032D
PIC32MX230F064D
PIC32MX230F256D
PIC32MX250F128D
PIC32MX270F256D

44 1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	RPB9/SDA1/CTED4/PMD3/RB9	23	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2
2	RPC6/PMA1/RC6	24	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3
3	RPC7/PMA0/RC7	25	AN6/RPC0/RC0
4	RPC8/PMA5/RC8	26	AN7/RPC1/RC1
5	RPC9/CTED7/PMA6/RC9	27	AN8/RPC2/PMA2/RC2
6	VSS	28	VDD
7	VCAP	29	VSS
8	PGED2/RPB10/D+/CTED11/RB10	30	OSC1/CLKI/RPA2/RA2
9	PGEC2/RPB11/D-/RB11	31	OSC2/CLKO/RPA3/RA3
10	VUSB3V3	32	TDO/RPA8/PMA8/RA8
11	AN11/RPB13/CTPLS/PMRD/RB13	33	SOSCI/RPB4/RB4
12	PGED4(4)/TMS/PMA10/RA10	34	SOSCO/RPA4/T1CK/CTED9/RA4
13	PGEC4(4)/TCK/CTED8/PMA7/RA7	35	TDI/RPA9/PMA9/RA9
14	CVREFOUT/AN10/C3INB/RPB14/VBUSON/SCK1/CTED5/RB14	36	AN12/RPC3/RC3
15	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15	37	RPC4/PMA4/RC4
16	AVSS	38	RPC5/PMA3/RC5
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	PGED3/VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/PMD7/RA0	41	RPB5/USBID/RB5
20	PGEC3/VREF-/CVREF-/AN1/RPA1/CTED2/PMD6/RA1	42	VBUS
21	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0	43	RPB7/CTED3/PMD5/INT0/RB7
22	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1	44	RPB8/SCL1/CTED10/PMD4/RB8

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: This pin function is not available on PIC32MX210F016D and PIC32MX220F032D devices.

5: Shaded pins are 5V tolerant.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number[1]				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
USBID	11[3]	14[3]	15[3]	41[3]	I	ST	USB OTG ID detect
CTED1	27	2	33	19	I	ST	CTMU External Edge Input
CTED2	28	3	34	20	I	ST	
CTED3	13	16	17	43	I	ST	
CTED4	15	18	19	1	I	ST	
CTED5	22	25	28	14	I	ST	
CTED6	23	26	29	15	I	ST	
CTED7	—	—	20	5	I	ST	
CTED8	—	—	—	13	I	ST	
CTED9	9	12	10	34	I	ST	
CTED10	14	17	18	44	I	ST	
CTED11	18	21	24	8	I	ST	
CTED12	2	5	36	22	I	ST	
CTED13	3	6	1	23	I	ST	
CTPLS	21	24	27	11	O	—	CTMU Pulse Output
PGED1	1	4	35	21	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 1
PGEC1	2	5	36	22	I	ST	Clock input pin for Programming/Debugging Communication Channel 1
PGED2	18	21	24	8	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 2
PGEC2	19	22	25	9	I	ST	Clock input pin for Programming/Debugging Communication Channel 2
PGED3	11[2]	14[2]	15[2]	41[2]	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 3
	27[3]	2[3]	33[3]	19[3]			
PGEC3	12[2]	15[2]	16[2]	42[2]	I	ST	Clock input pin for Programming/ Debugging Communication Channel 3
	28[3]	3[3]	34[3]	20[3]			
PGED4	—	—	3	12	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 4
PGEC4	—	—	4	13	I	ST	Clock input pin for Programming/ Debugging Communication Channel 4

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUs

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX1XX/2XX 28/36/44-pin Family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins, even if the ADC module is not used (see **2.2 "Decoupling Capacitors"**)
- VCAP pin (see **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**)
- $\overline{\text{MCLR}}$ pin (see **2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins, used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins, when external oscillator source is used (see **2.7 "External Oscillator Pins"**)

The following pins may be required:

- VREF+/VREF- pins – used when external voltage reference for the ADC module is implemented

Note: The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

TABLE 4-1: SFR MEMORY MAP

Peripheral	Virtual Address	
	Base	Offset Start
Watchdog Timer	0xBF80	0x0000
RTCC		0x0200
Timer1-5		0x0600
Input Capture 1-5		0x2000
Output Compare 1-5		0x3000
IC1 and IC2		0x5000
SPI1 and SPI2		0x5800
UART1 and UART2		0x6000
PMP		0x7000
ADC		0x9000
CVREF		0x9800
Comparator		0xA000
CTMU		0xA200
Oscillator		0xF000
Device and Revision ID		0xF220
Peripheral Module Disable		0xF240
Flash Controller		0xF400
Reset		0xF600
PPS		0xFA04
Interrupts	0xBF88	0x1000
Bus Matrix		0x2000
DMA		0x3000
USB		0x5050
PORTA-PORTC		0x6000
Configuration	0xBFC0	0x0BF0

REGISTER 4-3: BMXDUDBA: DATA RAM USER DATA BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDUDBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDUDBA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-10 **BMXDUDBA<15:10>:** DRM User Data Base Address bits

When non-zero, the value selects the relative base address for User mode data space in RAM, the value must be greater than BMXDKPBA.

bit 9-0 **BMXDUDBA<9:0>:** Read-Only bits

This value is always '0', which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernal mode data usage.

2: The value in this register must be less than or equal to BMXDRMSZ.

NOTES:

REGISTER 7-4: IFSx: INTERRUPT FLAG STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS31	IFS30	IFS29	IFS28	IFS27	IFS26	IFS25	IFS24
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS23	IFS22	IFS21	IFS20	IFS19	IFS18	IFS17	IFS16
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS15	IFS14	IFS13	IFS12	IFS11	IFS10	IFS09	IFS08
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS07	IFS06	IFS05	IFS04	IFS03	IFS02	IFS01	IFS00

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **IFS31-IFS00:** Interrupt Flag Status bits
1 = Interrupt request has occurred
0 = No interrupt request has occurred

Note: This register represents a generic definition of the IFSx register. Refer to Table 7-1 for the exact bit definitions.

REGISTER 7-5: IECx: INTERRUPT ENABLE CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC31	IEC30	IEC29	IEC28	IEC27	IEC26	IEC25	IEC24
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC23	IEC22	IEC21	IEC20	IEC19	IEC18	IEC17	IEC16
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC15	IEC14	IEC13	IEC12	IEC11	IEC10	IEC09	IEC08
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC07	IEC06	IEC05	IEC04	IEC03	IEC02	IEC01	IEC00

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **IEC31-IEC00:** Interrupt Enable bits
1 = Interrupt is enabled
0 = Interrupt is disabled

Note: This register represents a generic definition of the IECx register. Refer to Table 7-1 for the exact bit definitions.

REGISTER 9-7: DCHxCON: DMA CHANNEL 'x' CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
	CHBUSY	—	—	—	—	—	—	CHCHNS(1)
7:0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R-0	R/W-0	R/W-0
	CHEN(2)	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **CHBUSY:** Channel Busy bit
- 1 = Channel is active or has been enabled
- 0 = Channel is inactive or has been disabled

bit 14-9 **Unimplemented:** Read as '0'

bit 8 **CHCHNS:** Chain Channel Selection bit(1)
- 1 = Chain to channel lower in natural priority (CH1 will be enabled by CH2 transfer complete)
- 0 = Chain to channel higher in natural priority (CH1 will be enabled by CH0 transfer complete)

bit 7 **CHEN:** Channel Enable bit(2)
- 1 = Channel is enabled
- 0 = Channel is disabled

bit 6 **CHAED:** Channel Allow Events If Disabled bit
- 1 = Channel start/abort events will be registered, even if the channel is disabled
- 0 = Channel start/abort events will be ignored if the channel is disabled

bit **CHCHN:** Channel Chain Enable bit
- 1 = Allow channel to be chained
- 0 = Do not allow channel to be chained

bit 4 **CHAEN:** Channel Automatic Enable bit
- 1 = Channel is continuously enabled, and not automatically disabled after a block transfer is complete
- 0 = Channel is disabled on block transfer complete

bit 3 **Unimplemented:** Read as '0'

bit 2 **CHEDET:** Channel Event Detected bit
- 1 = An event has been detected
- 0 = No events have been detected

bit 1-0 **CHPRI<1:0>:** Channel Priority bits
- 11 = Channel has priority 3 (highest)
- 10 = Channel has priority 2
- 01 = Channel has priority 1
- 00 = Channel has priority 0

Note 1: The chain selection bit takes effect when chaining is enabled (i.e., CHCHN = 1).

2: When the channel is suspended by clearing this bit, the user application should poll the CHBUSY bit (if available on the device variant) to see when the channel is suspended, as it may take some clock cycles to complete a current transaction before the channel is suspended.

TABLE 11-4: PORTB REGISTER MAP

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6100	ANSELB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ANSB15	ANSB14	ANSB13	ANSB12(2)	—	—	—	—	—	—	—	—	ANSB3	ANSB2	ANSB1	ANSB0	E00F
6110	TRISB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TRISB15	TRISB14	TRISB13	TRISB12(2)	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6(2)	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
6120	PORTB	31:16	—	—	—	—	—	—	—	—	—	—	—						0000
		15:0	RB15	RB14	RB13	RB12(2)	RB11	RB10	RB9	RB8	RB7	RC6(2)	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
6130	LATB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	LATB15	LATB14	LATB13	LATB12(2)	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6(2)	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
6140	ODCB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ODCB15	ODCB14	ODCB13	ODCB12(2)	ODCB11	ODCB10	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	0000
6150	CNPUB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPUB15	CNPUB14	CNPUB13	CNPUB12(2)	CNPUB11	CNPUB10	CNPUB9	CNPUB8	CNPUB7	CNPUB6(2)	CNPUB5	CNPUB4	CNPUB3	CNPUB2	CNPUB1	CNPUB0	0000
6160	CNPDB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPDB15	CNPDB14	CNPDB13	CNPDB12(2)	CNPDB11	CNPDB10	CNPDB9	CNPDB8	CNPDB7	CNPDB6(2)	CNPDB5	CNPDB4	CNPDB3	CNPDB2	CNPDB1	CNPDB0	0000
6170	CNCONB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
6180	CNENB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNIEB15	CNIEB14	CNIEB13	CNIEB11(2)	CNIEB11	CNIEB10	CNIEB9	CNIEB8	CNIEB7	CNIEB6(2)	CNIEB5	CNIEB4	CNIEB3	CNIEB2	CNIEB1	CNIEB0	0000
6190	CNSTATB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CN STATB15	CN STATB14	CN STATB13	CN STATB12(2)	CN STATB11	CN STATB10	CN STATB9	CN STATB8	CN STATB7	CN STATB6(2)	CN STATB5	CN STATB4	CN STATB3	CN STATB2	CN STATB1	CN STATB0	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

2: This bit is not available on PIC32MX2XX devices. The reset value for the TRISB register when this bit is not available is 0x0000EFBF.

17.1 SPI Control Registers

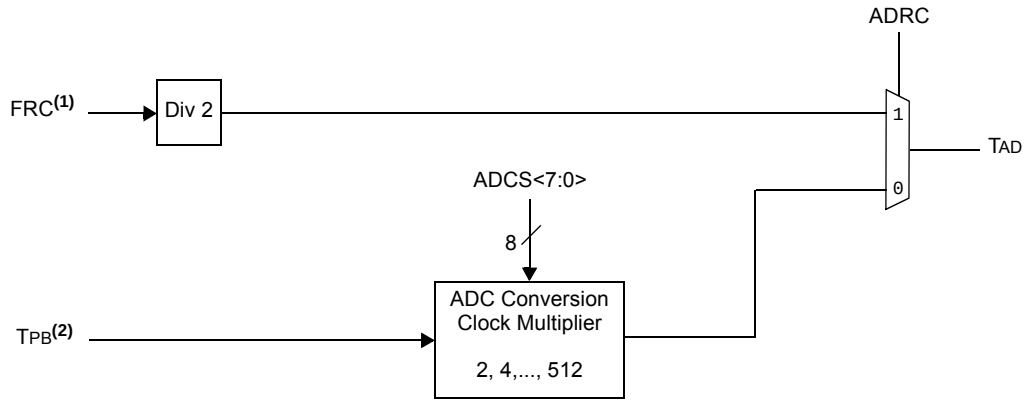
TABLE 17-1: SPI1 AND SPI2 REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5800	SPI1CON	31:16	FRMEN	FRMSYNC	FRMPOL	MSSEN	FRMSYPW	FRMCNT<2:0>			MCLKSEL	—	—	—	—	—	SPIFE	ENHBUF	0000
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	DISSDI	STXISEL<1:0>		SRXISEL<1:0>		0000
5810	SPI1STAT	31:16	—	—	—	RXBUFELM<4:0>					—	—	—	TXBUFELM<4:0>					0000
		15:0	—	—	—	FRMERR	SPIBUSY	—	—	SPITUR	SRMT	SPIROV	SPIRBE	—	SPITBE	—	SPITBF	SPIRBF	0008
5820	SPI1BUF	31:16	DATA<31:0>																0000
		15:0																	0000
5830	SPI1BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	BRG<12:0>													0000
5840	SPI1CON2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	SPI SGNEXT	—	—	FRM ERREN	SPI ROVEN	SPI TUREN	IGNROV	IGNTUR	AUDEN	—	—	—	AUD MONO	—	AUDMOD<1:0>		0000
5A00	SPI2CON	31:16	FRMEN	FRMSYNC	FRMPOL	MSSEN	FRMSYPW	FRMCNT<2:0>			MCLKSEL	—	—	—	—	—	SPIFE	ENHBUF	0000
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	DISSDI	STXISEL<1:0>		SRXISEL<1:0>		0000
5A10	SPI2STAT	31:16	—	—	—	RXBUFELM<4:0>					—	—	—	TXBUFELM<4:0>					0000
		15:0	—	—	—	FRMERR	SPIBUSY	—	—	SPITUR	SRMT	SPIROV	SPIRBE	—	SPITBE	—	SPITBF	SPIRBF	0008
5A20	SPI2BUF	31:16	DATA<31:0>																0000
		15:0																	0000
5A30	SPI2BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	BRG<12:0>													0000
5A40	SPI2CON2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	SPI SGNEXT	—	—	FRM ERREN	SPI ROVEN	SPI TUREN	IGNROV	IGNTUR	AUDEN	—	—	—	AUD MONO	—	AUDMOD<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table except SPIxBUF have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

FIGURE 22-2: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



Note 1: See **Section 30.0 "Electrical Characteristics"** for the exact FRC clock value.

2: Refer to Figure 8-1 in **Section 8.0 "Oscillator Configuration"** for more information.

25.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 37. "Charge Time Measurement Unit (CTMU)"** (DS60001167), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

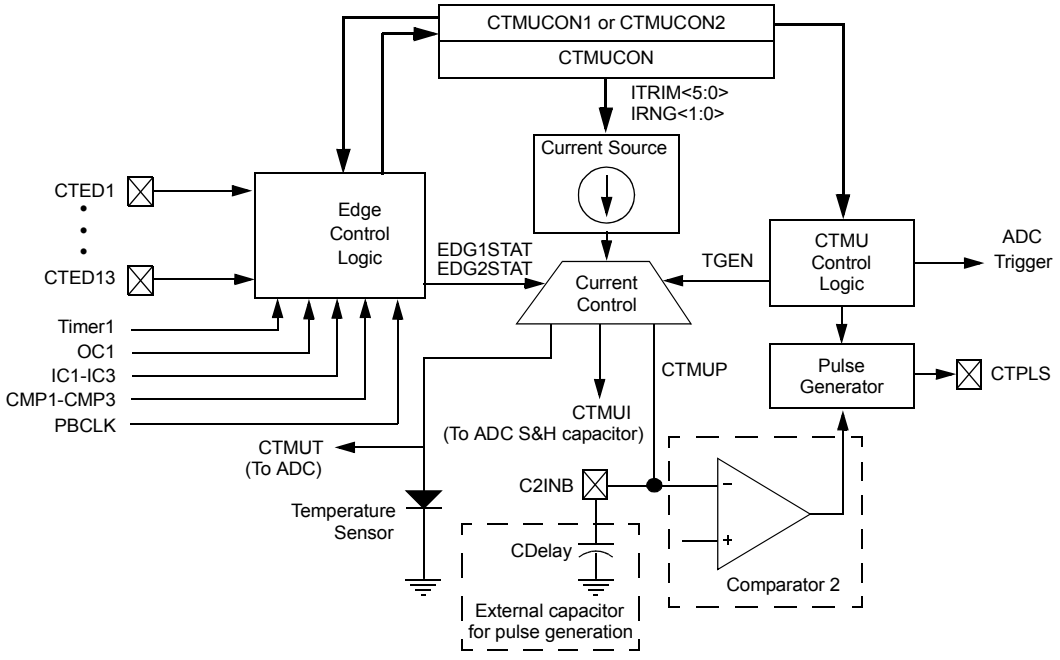
The Charge Time Measurement Unit (CTMU) is a flexible analog module that has a configurable current source with a digital configuration circuit built around it. The CTMU can be used for differential time measurement between pulse sources and can be used for generating an asynchronous pulse. By working with other on-chip analog modules, the CTMU can be used for high resolution time measurement, measure capacitance, measure relative changes in capacitance or generate output pulses with a specific time delay. The CTMU is ideal for interfacing with capacitive-based sensors.

The CTMU module includes the following key features:

- Up to 13 channels available for capacitive or time measurement input
- On-chip precision current source
- 16-edge input trigger sources
- Selection of edge or level-sensitive inputs
- Polarity control for each edge source
- Control of edge sequence
- Control of response to edges
- High precision time measurement
- Time delay of external or internal signal asynchronous to system clock
- Integrated temperature sensing diode
- Control of current source during auto-sampling
- Four current source ranges
- Time measurement resolution of one nanosecond

A block diagram of the CTMU is shown in Figure 25-1.

FIGURE 25-1: CTMU BLOCK DIAGRAM



Current Control Selection	TGEN	EDG1STAT, EDG2STAT
CTMUT	0	EDG1STAT = EDG2STAT
CTMUI	0	EDG1STAT ≠ EDG2STAT
CTMUP	1	EDG1STAT ≠ EDG2STAT
No Connect	1	EDG1STAT = EDG2STAT

TABLE 30-9: DC CHARACTERISTICS: I/O PIN INPUT INJECTION CURRENT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
DI60a	IICL	**Input Low Injection Current**	0	—	-5(2,5)	mA	This parameter applies to all pins, with the exception of the power pins.
DI60b	IICH	**Input High Injection Current**	0	—	+5(3,4,5)	mA	This parameter applies to all pins, with the exception of all 5V tolerant pins, and the SOSCI, SOSCO, OSC1, D+, and D- pins.
DI60c	∑IICT	**Total Input Injection Current (sum of all I/O and Control pins)**	-20(6)	—	+20(6)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| IICL + | IICH |) ≤ ∑IICT)

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: VIL source < (VSS - 0.3). Characterized but not tested.

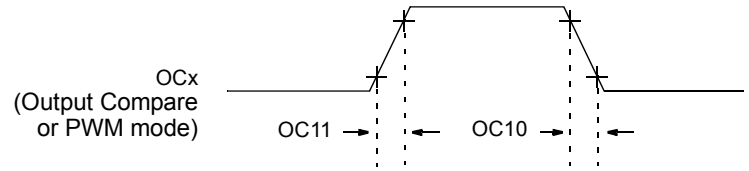
3: VIH source > (VDD + 0.3) for non-5V tolerant pins only.

4: Digital 5V tolerant pins do not have an internal high side diode to VDD, and therefore, cannot tolerate any "positive" input injection current.

5: Injection currents > | 0 | can affect the ADC results by approximately 4 to 6 counts (i.e., VIH Source > (VDD + 0.3) or VIL source < (VSS - 0.3)).

6: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. If **Note 2**, IICL = (((Vss - 0.3) - VIL source) / Rs). If **Note 3**, IICH = ((IICH source - (VDD + 0.3)) / RS). RS = Resistance between input source voltage and device pin. If (VSS - 0.3) ≤ VSOURCE ≤ (VDD + 0.3), injection current = 0.

FIGURE 30-8: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

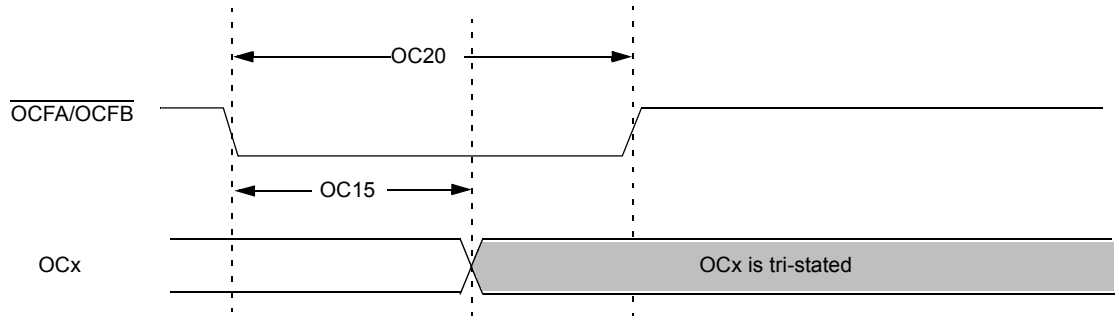
TABLE 30-26: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See parameter DO31

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 30-9: OCx/PWM MODULE TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-27: SIMPLE OCx/PWM MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param No.	**Symbol**	**Characteristics(1)**	**Min**	**Typical(2)**	**Max**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWM I/O Change	—	—	50	ns	—
OC20	TFLT	Fault Input Pulse Width	50	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 31-5: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
MOS10	FOSC	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50 50	MHz MHz	EC **(Note 2)** ECPLL **(Note 1)**

Note 1: PLL input requirements: 4 MHz ≤ FPLLIN ≤ 5 MHz (use PLL prescaler to reduce Fosc). This parameter is characterized, but tested at 10 MHz only at manufacturing.

2: This parameter is characterized, but not tested in manufacturing.

TABLE 31-6: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
MSP10	TscL	SCKx Output Low Time **(Note 1,2)**	TSCK/2	—	—	ns	—
MSP11	TscH	SCKx Output High Time **(Note 1,2)**	TSCK/2	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

TABLE 31-7: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
MSP10	TscL	SCKx Output Low Time **(Note 1,2)**	TSCK/2	—	—	ns	—
MSP11	TscH	SCKx Output High Time **(Note 1,2)**	TSCK/2	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

FIGURE 32-6: TYPICAL FRC FREQUENCY @ VDD = 3.3V

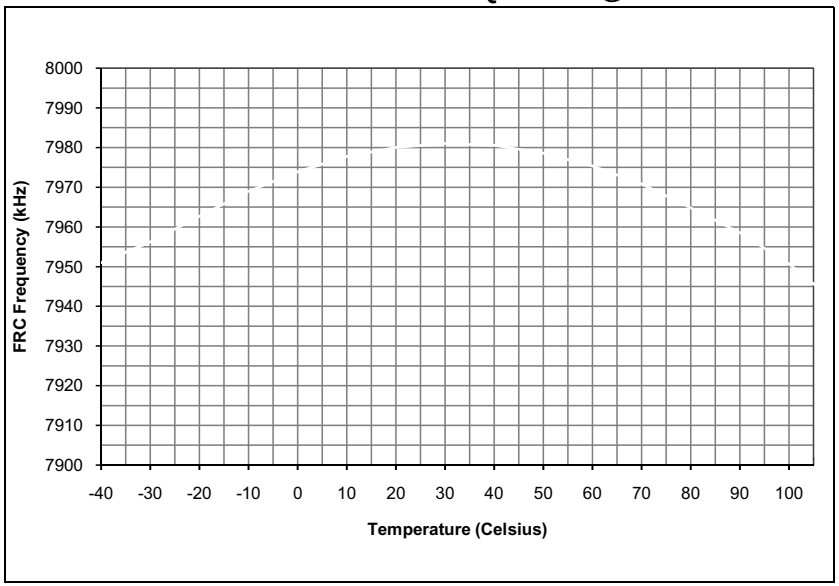


FIGURE 32-7: TYPICAL LPRC FREQUENCY @ VDD = 3.3V

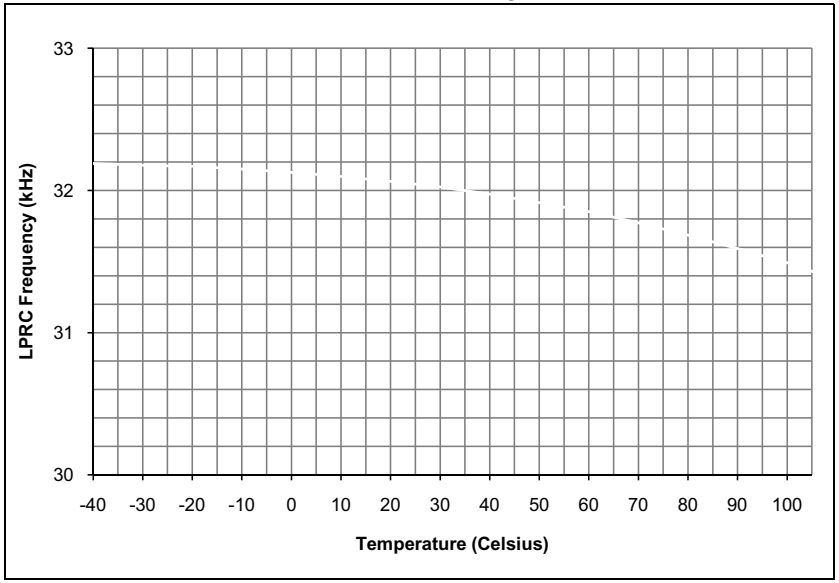
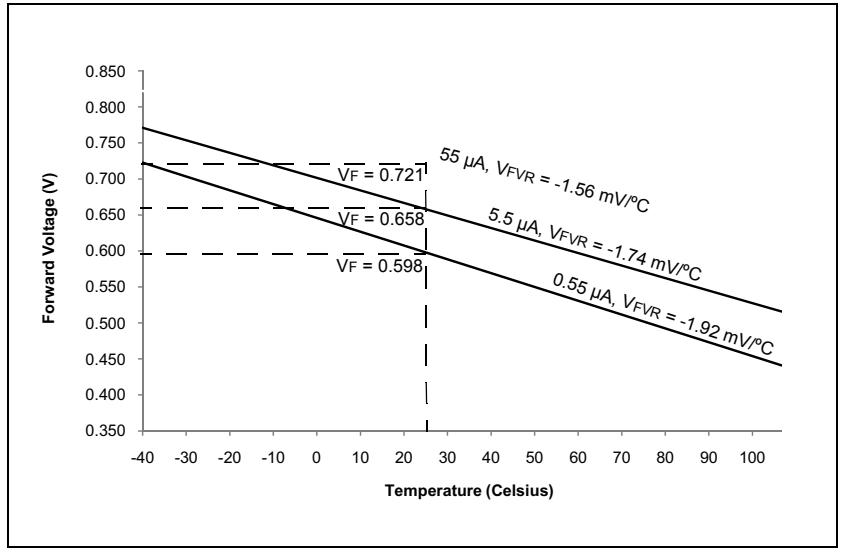
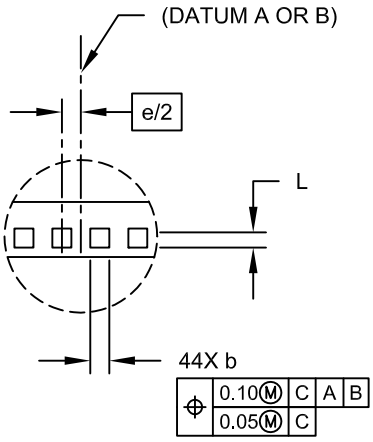


FIGURE 32-8: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE

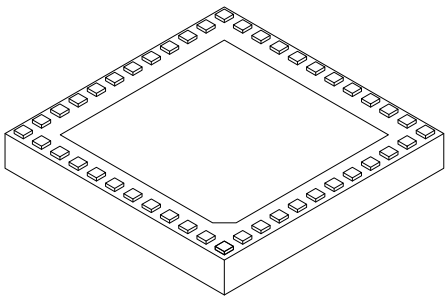


44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		44	
Number of Pins per Side	ND		12	
Number of Pins per Side	NE		10	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.40	4.55	4.70
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.40	4.55	4.70
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-157C Sheet 2 of 2

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section	Update Description
4.0 "Memory Organization"	Added Memory Maps for the new devices (see Figure 4-3 and Figure 4-4). Removed the BMXCHEDMA bit from the Bus Matrix Register map (see Table 4-1). Added the REFOTRIM register, added the DIVSWEN bit to the REFOCON registers, added Note 4 to the ULOCK and SOSCEN bits and added the PBDIVRDY bit in the OSCCON register in the in the System Control Register map (see Table 4-16). Removed the ALTI2C1 and ALTI2C2 bits from the DEVCFG3 register and added Note 1 to the UPLLEN and UPLLIDIV<2:0> bits of the DEVCFG2 register in the Device Configuration Word Summary (see Table 4-17). Updated Note 1 in the Device and Revision ID Summary (see Table 4-18). Added Note 2 to the PORTA Register map (see Table 4-19). Added the ANSB6 and ANSB12 bits to the ANSELB register in the PORTB Register map (see Table 4-20). Added Notes 2 and 3 to the PORTC Register map (see Table 4-21). Updated all register names in the Peripheral Pin Select Register map (see Table 4-23). Added values in support of new devices (16 KB RAM and 32 KB RAM) in the Data RAM Size register (see Register 4-5). Added values in support of new devices (64 KB Flash and 128 KB Flash) in the Data RAM Size register (see Register 4-5).
8.0 "Oscillator Configuration"	Added Note 5 to the PIC32MX1XX/2XX Family Clock Diagram (see Figure 8-1). Added the PBDIVRDY bit and Note 2 to the Oscillator Control register (see Register 8-1). Added the DIVSWEN bit and Note 3 to the Reference Oscillator Control register (see Register 8-3). Added the REFOTRIM register (see Register 8-4).
21.0 "10-bit Analog-to-Digital Converter (ADC)"	Updated the ADC1 Module Block Diagram (see Figure 21-1). Updated the Notes in the ADC Input Select register (see Register 21-4).
24.0 "Charge Time Measurement Unit (CTMU)"	Updated the CTMU Block Diagram (see Figure 24-1). Added Note 3 to the CTMU Control register (see Register 24-1)
26.0 "Special Features"	Added Note 1 and the PGEC4/PGED4 pin pair to the ICESEL<1:0> bits in DEVCFG0: Device Configuration Word 0 (see Register 26-1). Removed the ALTI2C1 and ALTI2C2 bits from the Device Configuration Word 3 register (see Register 26-4). Removed 26.3.3 "Power-up Requirements". Added Note 3 to the Connections for the On-Chip Regulator diagram (see Figure 26-2). Updated the Block Diagram of Programming, Debugging and Trace Ports diagram (see Figure 26-3).

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section	Update Description
29.0 "Electrical Characteristics"	Updated the Absolute Maximum Ratings (removed Voltage on VCORE with respect to VSS). Added the SPDIP specification to the Thermal Packaging Characteristics (see Table 29-2). Updated the Typical values for parameters DC20-DC24 in the Operating Current (IDD) specification (see Table 29-5). Updated the Typical values for parameters DC30a-DC34a in the Idle Current (IIDLE) specification (see Table 29-6). Updated the Typical values for parameters DC40i and DC40n and removed parameter DC40m in the Power-down Current (IPD) specification (see Table 29-7). Removed parameter D320 (VCORE) from the Internal Voltage Regulator Specifications and updated the Comments (see Table 29-13). Updated the Minimum, Typical, and Maximum values for parameter F20b in the Internal FRC Accuracy specification (see Table 29-17). Removed parameter SY01 (TPWRT) and removed all Conditions from Resets Timing (see Table 29-20). Updated all parameters in the CTMU Specifications (see Table 29-39).
31.0 "Packaging Information"	Added the 28-lead SPDIP package diagram information (see **31.1 "Package Marking Information"** and **31.2 "Package Details"**).
"Product Identification System**"**	Added the SPDIP (SP) package definition.

Revision C (November 2011)

All major changes are referenced by their respective section in Table A-2.

TABLE A-2: MAJOR SECTION UPDATES

Section	Update Description
"32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog**"**	Revised the source/sink on I/O pins (see **"Input/Output"** on page 1). Added the SPDIP package to the PIC32MX220F032B device in the PIC32MX2XX USB Family Features (see Table 2).
4.0 "Memory Organization"	Removed ANSB6 from the ANSELB register and added the ODCB6, ODCB10, and ODCB11 bits in the PORTB Register Map (see Table 4-20).
29.0 "Electrical Characteristics"	Updated the minimum value for parameter OS50 in the PLL Clock Timing Specifications (see Table 29-16).

Revision D (February 2012)

All occurrences of VUSB were changed to: VUSB3V3. In addition, text and formatting changes were incorporated throughout the document.

All other major changes are referenced by their respective section in Table A-3.

TABLE A-3: MAJOR SECTION UPDATES

Section	Update Description
"32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog**"**	Corrected a part number error in all pin diagrams. Updated the DMA Channels (Programmable/Dedicated) column in the PIC32MX1XX General Purpose Family Features (see Table 1).
1.0 "Device Overview"	Added the TQFP and VTLA packages to the 44-pin column heading and updated the pin numbers for the SCL1, SCL2, SDA1, and SDA2 pins in the Pinout I/O Descriptions (see Table 1-1).
7.0 "Interrupt Controller"	Updated the Note that follows the features. Updated the Interrupt Controller Block Diagram (see Figure 7-1).
29.0 "Electrical Characteristics"	Updated the Maximum values for parameters DC20-DC24, and the Minimum value for parameter DC21 in the Operating Current (IDD) DC Characteristics (see Table 29-5). Updated all Minimum and Maximum values for the Idle Current (IIDLE) DC Characteristics (see Table 29-6). Updated the Maximum values for parameters DC40k, DC40l, DC40n, and DC40m in the Power-down Current (IPD) DC Characteristics (see Table 29-7). Changed the minimum clock period for SCKx from 40 ns to 50 ns in Note 3 of the SPIx Master and Slave Mode Timing Requirements (see Table 29-26 through Table 29-29).
30.0 "DC and AC Device Characteristics Graphs"	Updated the Typical IIDLE Current @ VDD = 3.3V graph (see Figure 30-5).